

IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Xiang Dai et al.

Confirmation No.: 5441

Application No.: 10/612,663

Examiner: James Mitchell

Filing Date: 7/2/2003

Group Art Unit: 2813

Title: SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE HAVING A SOLDER COLUMN ARRAY

Mail Stop Amendment
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- (X) Response/Amendment () Petition to extend time to respond
() New fee as calculated below () Supplemental Declaration
(X) No additional fee
(X) Other: 2 RETURN RECEIPT POSTCARDS (fee \$)

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	15	MINUS	20	= 0	X \$50	\$ 0
INDEP. CLAIMS	4	MINUS	4	= 0	X \$200	\$ 0
[] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ \$360	\$ 0
EXTENSION FEE	1ST MONTH \$120.00	2ND MONTH \$450.00	3RD MONTH \$1020.00	4TH MONTH \$1590.00		\$ 0
OTHER FEES						\$
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 0

Charge \$ 0 to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16 through 1.21 inclusive, and any other sections in Title 37 of the Code of Federal Regulations that may regulate fees. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

Xiang Dai et al.

By

Paul S. Grunzweig

Attorney/Agent for Applicant(s)

Reg. No. 37,143

Date: 11/8/2005

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450.

Date of Deposit: 11/8/2005

Typed Name: Paul S. Grunzweig

Signature:

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant: Xiang Dai et al.

Examiner: James M. Mitchell

Serial No.: 10/612,663

Group Art Unit: 2813

Filed: July 2, 2003

Docket No.: 200308566-1/H300.211.101

Title: SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE
HAVING A SOLDER COLUMN ARRAY

AMENDMENT AND RESPONSE

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Amendment and Response is in reply to the Office Action mailed August 8, 2005. Please amend the above-identified patent application as follows: